

DIVIDING METHOD OF WORKPIECE, DETECTION METHOD OF DIMENSIONS OF CHIPS, AND CUTTING APPARATUS

ABSTRACT OF THE DISCLOSURE

A cutting apparatus includes a holding unit that holds a workpiece having electrodes in each of plural regions marked out by plural planned dividing lines that intersect each other and a cutting unit to which a cutting blade that cuts the workpiece held by the holding unit is mounted. The cutting apparatus includes also an imaging unit that images the workpiece and a control unit that controls the holding unit and the cutting unit. A dividing method includes a dividing step of cutting the workpiece by the cutting blade along the planned dividing lines to divide the workpiece into plural chips, an image acquisition step of imaging the chips by the imaging unit and acquiring an image of the chips, and a detection step of detecting actual dimensions of the chips by the control unit based on the image.

[Fig. 1]